



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20140306003
Qualification of RFAB as an additional FAB site option for the
TPS22913BYZVR/T and TLS2700RGTRG4 devices
Change Notification / Sample Request

Date: 3/13/2014
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20140306003
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TPS22913BYZVR	null
TPS22913BYZVT	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	PCN20140306003		PCN Date:	03/13/2014										
Title:	Qualification of RFAB as an additional FAB site option for the TPS22913BYZVR/T and TLS2700RGTRG4 devices													
Customer Contact:	PCN Manager	Phone:	+1(214)480-6037	Dept:	Quality Services									
*Proposed 1st Ship Date:	06/13/2014		Estimated Sample Availability:	Date provided at sample request.										
Change Type:														
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials									
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification									
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process									
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process									
<input checked="" type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process									
<input type="checkbox"/>		<input type="checkbox"/>	Part number change	<input type="checkbox"/>										
PCN Details														
Description of Change:														
Texas Instruments is pleased to announce the qualification of its RFAB fabrication facility as an additional wafer FAB source for the TPS22913BYZVR/T and TLS2700RGTRG4 devices.														
<table border="1"> <thead> <tr> <th>Device Name</th> <th>Qualified Site, Process, Wafer Dia.</th> <th>Additional Site, Process, Wafer Dia.</th> </tr> </thead> <tbody> <tr> <td>TPS22913BYZVR/T</td> <td>FR-BIP-1, LBC7 Process, 200mm</td> <td>RFAB, LBC7 Process, 300mm</td> </tr> <tr> <td>TLS2700RGTRG4</td> <td>MIHO8, LBC7 Process, 200mm</td> <td>RFAB, LBC7 Process, 300mm</td> </tr> </tbody> </table>						Device Name	Qualified Site, Process, Wafer Dia.	Additional Site, Process, Wafer Dia.	TPS22913BYZVR/T	FR-BIP-1, LBC7 Process, 200mm	RFAB, LBC7 Process, 300mm	TLS2700RGTRG4	MIHO8, LBC7 Process, 200mm	RFAB, LBC7 Process, 300mm
Device Name	Qualified Site, Process, Wafer Dia.	Additional Site, Process, Wafer Dia.												
TPS22913BYZVR/T	FR-BIP-1, LBC7 Process, 200mm	RFAB, LBC7 Process, 300mm												
TLS2700RGTRG4	MIHO8, LBC7 Process, 200mm	RFAB, LBC7 Process, 300mm												
The LBC7 process was previously qualified at RFAB on 10/06/2010. Qual details are shown in the Qual Data Section of this document.														
Reason for Change:														
Continuity of Supply														
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):														
None														
Changes to product identification resulting from this PCN:														
Current														
<table border="1"> <thead> <tr> <th>Chip Site</th> <th>Chip site code (20L)</th> <th>Chip country code (21L)</th> </tr> </thead> <tbody> <tr> <td>FR-BIP-1</td> <td>TID</td> <td>DEU</td> </tr> <tr> <td>MIHO 8</td> <td>MH8</td> <td>JPN</td> </tr> </tbody> </table>						Chip Site	Chip site code (20L)	Chip country code (21L)	FR-BIP-1	TID	DEU	MIHO 8	MH8	JPN
Chip Site	Chip site code (20L)	Chip country code (21L)												
FR-BIP-1	TID	DEU												
MIHO 8	MH8	JPN												
New														
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Chip Site	Chip site code (20L)	Chip country code (21L)												
RFAB	RFB	USA												

Sample product shipping label (not actual product label)

TEXAS INSTRUMENTS

MADE IN: Malaysia

2DC: 20:



MSL 2 / 260C / 1 YEAR	SEAL DT
MSL 1 / 235C / UNLIM	03/29/04

OPT:
ITEM: 39
LBL: 5A (L) TO: 1750

(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T) LOT: 3959047MLA
(4W) TKY (1T) 7523483S12
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO: USA
(22L) ASO: MLA (23L) ACO: MYS

Product Affected:

TLS2700RGTRG4	TPS22913BYZVR	TPS22913BYZVT
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Qualification Data: (Approved: 01/15/2014)

This qualification has been developed for the validation of this change. The qualification data will validate that the proposed change meets the applicable released technical specifications.

Qualification Device: TLS2700RGT

Wafer Fab Site: RFAB	Wafer Fab Process: LBC7
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Qualification: Plan Test Results

Reliability Test	Conditions	Sample Size Lot#1
Electrical Characterization	-	Pass
Latch-up	(per JESD78)	6/0
ESD HBM	1000V	3/0
ESD CDM	500V	3/0
Life Test	125C (1000 Hrs)	77/0

Qualification Data: (Approved: 2/20/2014)

This qualification has been developed for the validation of this change. The qualification data will validate that the proposed change meets the applicable released technical specifications.

Qualification Device: TPS22913BYZVR

Wafer Fab Site: RFAB	Wafer Fab Process: LBC7
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Qualification: Plan Test Results

Reliability Test	Conditions	Sample Size Lot#1
Electrical Characterization	-	Pass
Latch-up	(per JESD78, Class II)	6/0
ESD HBM	1000V	3/0
ESD CDM	250V	3/0

RFAB LBC7 Qualification Data: (Approved: 10/06/2010)

This qualification has been developed for the validation of this change. The qualification data will validate that the proposed change meets the applicable released technical specifications.

Qualification Device: TPS51217DSC

Wafer Fab Site: RFAB Wafer Fab Process: LBC7

Qualification: Plan **Test Results**

Reliability Test	Conditions	Sample Size		
		Lot#1	Lot#2	Lot#3
Electrical Char.	-	Pass	Pass	Pass
Latch-up	(per JESD78)	6/0	6/0	6/0
**Biased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0
Post Temp Cycle SAM	CSAM and TSAM analysis after 1000 cycles Temp cycle	Pass	Pass	Pass
ESD HBM	2000V	3/0	3/0	3/0
ESD CDM	500V	3/0	3/0	3/0
Wafer Fab MQ	Per site spec	Pass	-	-
Assembly / Test MQ	(per mfg. Site specification)	Pass	Pass	Pass
Wafer level Reliability	Approved by TDQRE	Pass	-	-
High Temp. Storage Bake	170C (168, 420 Hrs)	77/0	77/0	77/0
**Autoclave 121C	121C, (96 Hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500, 1000 Cycles)	77/0	77/0	77/0
Steady-state Life Test (See Note 1)	135C (110, 320, 635 Hrs)	77/0	77/0	77/0
**Preconditioning: MSL 2@260C				

Note 1: Life test equivalent conditions

125C, 1000hrs

135C, 635hrs

140C, 480hrs

150C, 300hrs

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com